



## mSMD350

### Performance Specification

Model	$V_{max}$ (Vdc)	$I_{max}$ (A)	$I_{hold}$ @25°C (A)	$I_{trip}$ @25°C (A)	$P_d$ Typ. (W)	Maximum Time To Trip		Resistance		Agency Approval	
						Current (A)	Time (Sec)	$R_{imin}$ ( $\Omega$ )	$R1_{max}$ ( $\Omega$ )	UL	TUV
mSMD350	6.0	100	3.50	6.00	2.0	10.0	4.00	0.008	0.030		

**I<sub>hold</sub>** = Hold Current. Maximum current device will not trip in 25°C still air.  
**I<sub>trip</sub>** = Trip Current. Minimum current at which the device will always trip in 25°C still air.  
**V<sub>max</sub>** = Maximum operating voltage device can withstand without damage at rated current ( $I_{max}$ ).  
**I<sub>max</sub>** = Maximum fault current device can withstand without damage at rated voltage ( $V_{max}$ ).  
**P<sub>d</sub>** = Power dissipation when device is in the tripped state in 25°C still air environment at rated voltage.  
**R<sub>imin</sub>/max** = Minimum/Maximum device resistance prior to tripping at 25°C.  
**R1<sub>max</sub>** = Maximum device resistance is measured one hour post reflow.  
**CAUTION** : Operation beyond the specified ratings may result in damage and possible arcing and flame.

### Environmental Specifications

Test	Conditions	Resistance change
Passive aging	+85°C, 1000 hrs.	±5% typical
Humidity aging	+85°C, 85% R.H. , 168 hours	±5% typical
Thermal shock	+85°C to -40°C, 20 times	±33% typical
Resistance to solvent	MIL-STD-202,Method 215	No change
Vibration	MIL-STD-202,Method 201	No change
Ambient operating conditions : - 40 °C to +85 °C		
Maximum surface temperature of the device in the tripped state is 125 °C		

Agency Approvals :

UL pending

Regulation/Standard:



2002/95/EC



EN14582

### $I_{hold}$ Versus Temperature

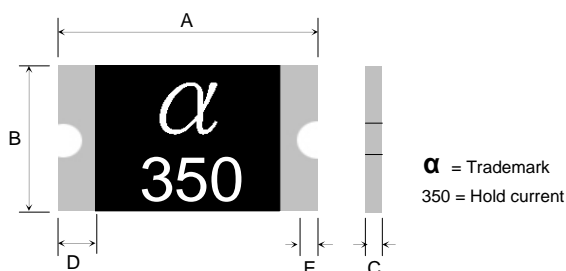
Model	Maximum ambient operating temperature ( $T_{mao}$ ) vs. hold current ( $I_{hold}$ )								
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
mSMD350	4.84	4.39	4.04	3.50	2.98	2.66	2.35	1.88	1.55

# mSMD350

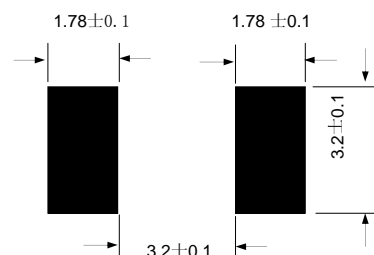
## Construction And Dimension (Unit:mm)

Model	A		B		C		D		E	
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.
mSMD350	4.37	4.73	3.07	3.41	0.50	1.50	0.30	0.30	0.25	0.25

## Dimensions & Marking



## Recommended Pad Layout (mm)



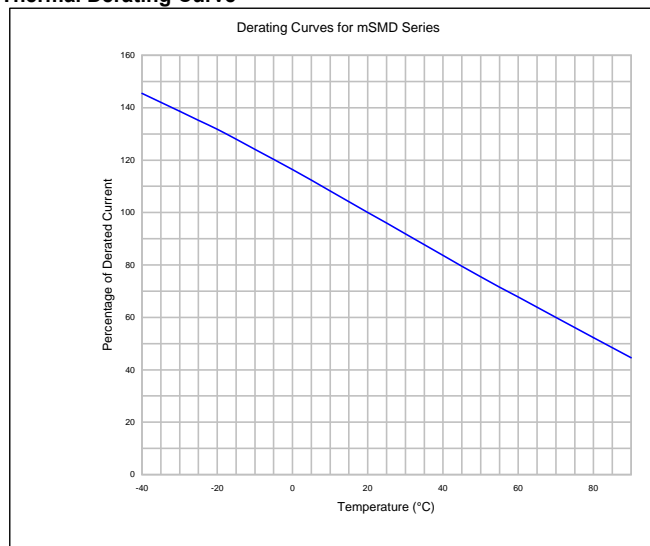
## Termination Pad Characteristics

Terminal pad materials : Tin-plated Nickel-Copper  
Terminal pad solderability : Meets EIA specification RS186-9E and ANSI/J-STD-002 Category 3.

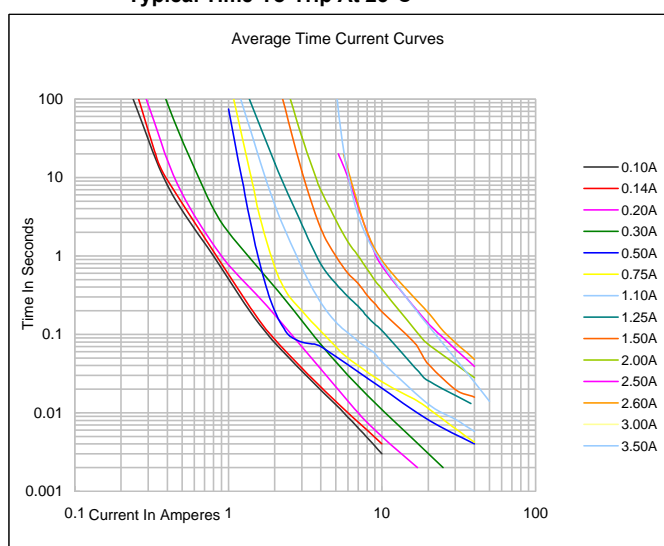
## Rework

Use standard industry practices, the removal device must be replaced with a fresh one.

## Thermal Derating Curve



## Typical Time-To-Trip At 25°C

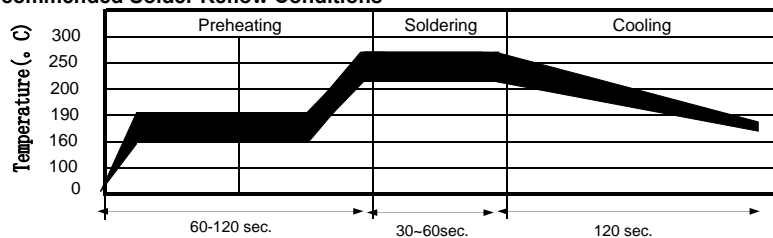


## WARNING:

- Use PPTC beyond the maximum ratings or improper use may result in device damage and possible electrical arcing and flame.
- PPTC are intended for protection against occasional over current or over temperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.
- Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components.
- Use PPTC with a large inductance in circuit will generate a circuit voltage (L di/dt) above the rated voltage of the PPTC.
- Avoid impact PPTC device its thermal expansion like placed under pressure or installed in limited space.
- Contamination of the PPTC material with certain silicon based oils or some aggressive solvents can adversely impact the performance of the devices. PPTC SMD can be cleaned by standard methods.
- Requests that customers comply with our recommended solder pad layouts and recommended reflow profile. Improper board layouts or reflow profile could negatively impact solderability.

# mSMD350

## Recommended Solder Reflow Conditions

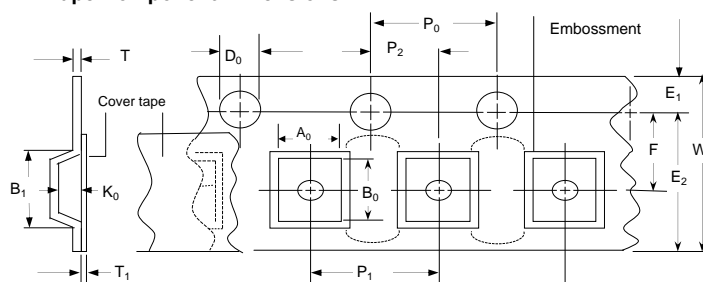


- Recommended reflow methods : IR, vapor phase oven, hot air oven.
  - Devices are not designed to be wave soldered to the bottom side of the board.
  - Recommended maximum paste thickness is 0.25 mm (0.010 inch).
  - Devices can be cleaned using standard method and solvents.
- Note : If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

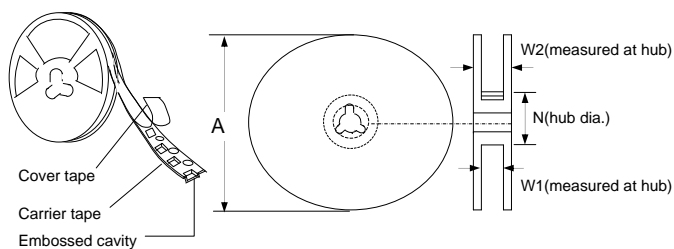
## Tape And Reel Specifications (mm)

Governing Specifications	EIA 481-1
W	12 ± 0.3
P0	4.0 ± 0.10
P1	8.0 ± 0.10
P2	2.0 ± 0.05
A0	3.5 ± 0.23
B0	5.1 ± 0.15
B1max.	5.9
D0	1.5 + 0.1, -0
F	5.5 ± 0.05
E1	1.75 ± 0.10
E2min.	10.25
Tmax.	0.6
T1max.	0.1
K0	0.9 ± 0.15
Leader min.	390
Trailer min.	160
Reel Dimensions	
A max.	178
N min.	60
W1	12.4 + 2.0, -0.0
W2max.	18.4

## EIA Tape Component Dimensions



## EIA Reel Dimensions



## Storage And Handling

- Storage conditions : 40°C max, 70% R.H.
- Devices may not meet specified performance if storage conditions are exceeded.

## Order Information

## Packaging

mSMD	350	Tape & Reel Quantity
Product name	Hold	
Size 4532mm/1812 inch	Current	
SMD : surface mount device	3.50A	1,500 pcs/reel